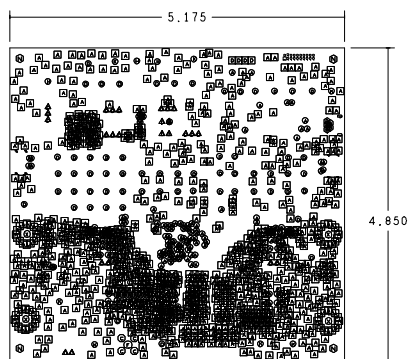


# NOTES:

- THIS IS 8 LAYER BOARD WITH COMPONENTS ON BOTH SIDES.
- PRINTED CIRCUIT BOARD SHALL BE 1 OZ COPPER ON ALL THE LAYERS  
BOARD MATERIAL TO BE EXPOXY BASED FR-4.
- SMOBC SOLDERMASK BOTH SIDES USING BLUE RESIST. IAW IPC-SM-840
- SILKSCREEN BOTH SIDE(S) USING WHITE NON CONDUCTIVE EPOXY BASED INK. TRIM ALL SILKSCREEN 4mils FROM BARE COPPER
- MANUFACTURE/FABRICATE TO MEET EU RoHS DIRECTIVE.  
ALL MATERIALS AND SOLDERMASK TO BE COMPLIANT TO EU RoHS  
DIRECTIVE 20002/95/EC  
LAMINATE AND RESIN MATERIAL PARAMETERS  
Tg > 170 C  
Td > 294 C
- ELECTROLESS NICKEL GOLD OR IMMERSION GOLD BOARD FINISH.
- MINIMUM TRACE WIDTH 6 MILS/ SPACE 4 MILS

NOTE: All VIAS to be TENTED. NO exposed copper pads on any  
VIAS top or bottom Except VIAS in SMT pads.



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	FINISHED SIZE	PLATED	QTY
•	10.0	PLATED	223
◻	18.0	PLATED	1047
•	23.0	PLATED	19
•	23.0	PLATED	1
•	28.0	PLATED	5
•	37.0	PLATED	4
•	40.0	PLATED	63
•	41.0	PLATED	25
•	42.0	PLATED	4
•	65.0	PLATED	3
•	65.0	PLATED	1
•	100.0	PLATED	7
•	155.0	PLATED	4
•	128.0	NON-PLATED	4
•	47.24x19.69	PLATED	8
•	76.0x28.0	PLATED	2

TOTAL HOLES: 1420

VIAS in SMT pads need to be epoxy filled.

Drawn By: M.Savio	Date Drawn: 02/21/2024	Engineer: Rahul Ramesh, Bonhyun Ku
Released By:	Date Released:	RTKA489301DE0000BU_Dual_FETs
Updated By:	Date Updated:	
	MASK#	HW# ID Updated By: REV. A
FILENAME: RTKA489301DE0000BU_Dual_FETs_revA		SHEET 1 OF 1